

Atty. Docket No. CPAC 1029-7
Appl. No. 10/681,584



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/681,584

Filed: October 8, 2003

Title: **Semiconductor multi-package
module having inverted second package
and including additional die or stacked
package on second package**

Examiner: Alonzo Chambliss

Group Art Unit: 2814

Date: 10 October 2005

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 10 October 2005.

Signed

Bill Kennedy

AMENDMENT

Dear Sir:

Responsive to the Office action mailed August 4, 2005, kindly amend the application as follows.

Amendments to the Claims are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.